



SOT137-1

plastic small outline package; 24 leads; body width 7.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO24
Package type industry code	SO24
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	075E05
JEDEC package outline code	MS-013
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

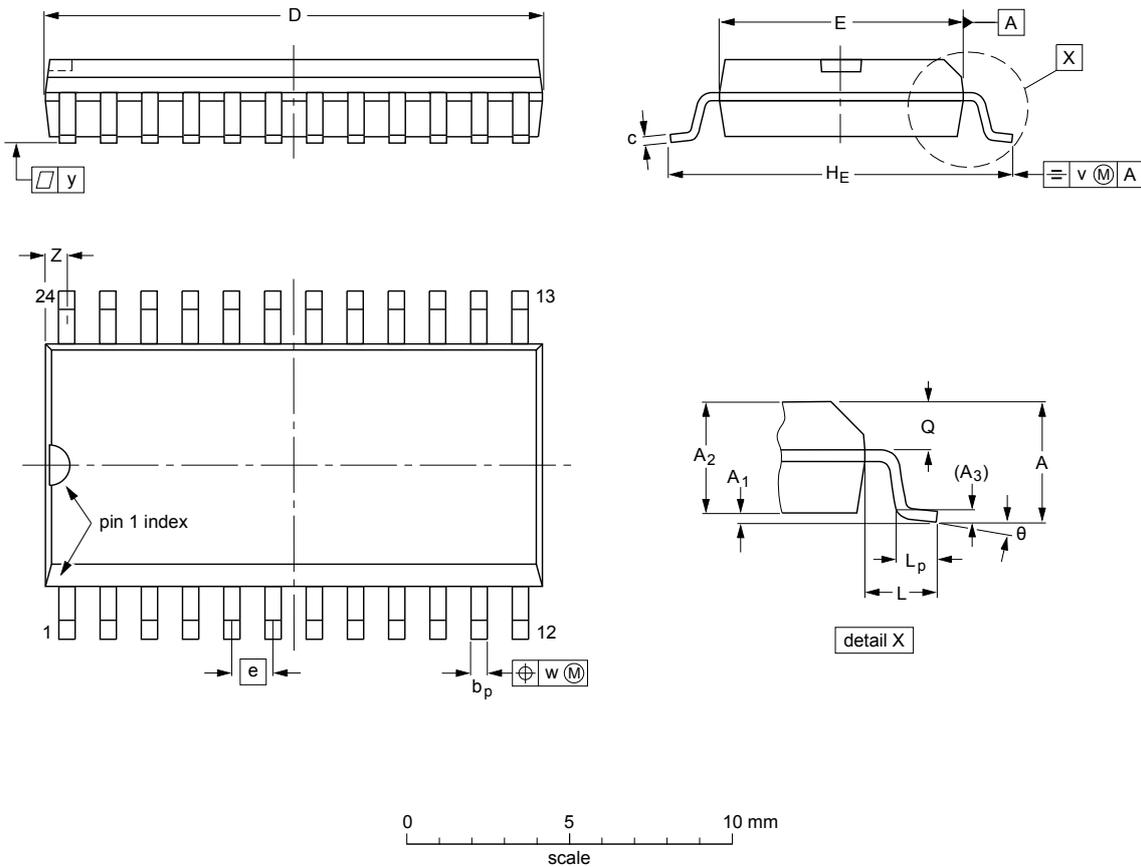
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.2	-	15.3	15.6	mm
E	package width	7.4	-	7.5	7.6	mm
A	seated height	[tbd]	-	2.65	2.65	mm
A ₂	package height	2.25	-	2.35	2.45	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT137-1	075E05	MS-013			-99-12-27 03-02-19

Fig. 1. Package outline SO24 (SOT137-1)

3. Soldering

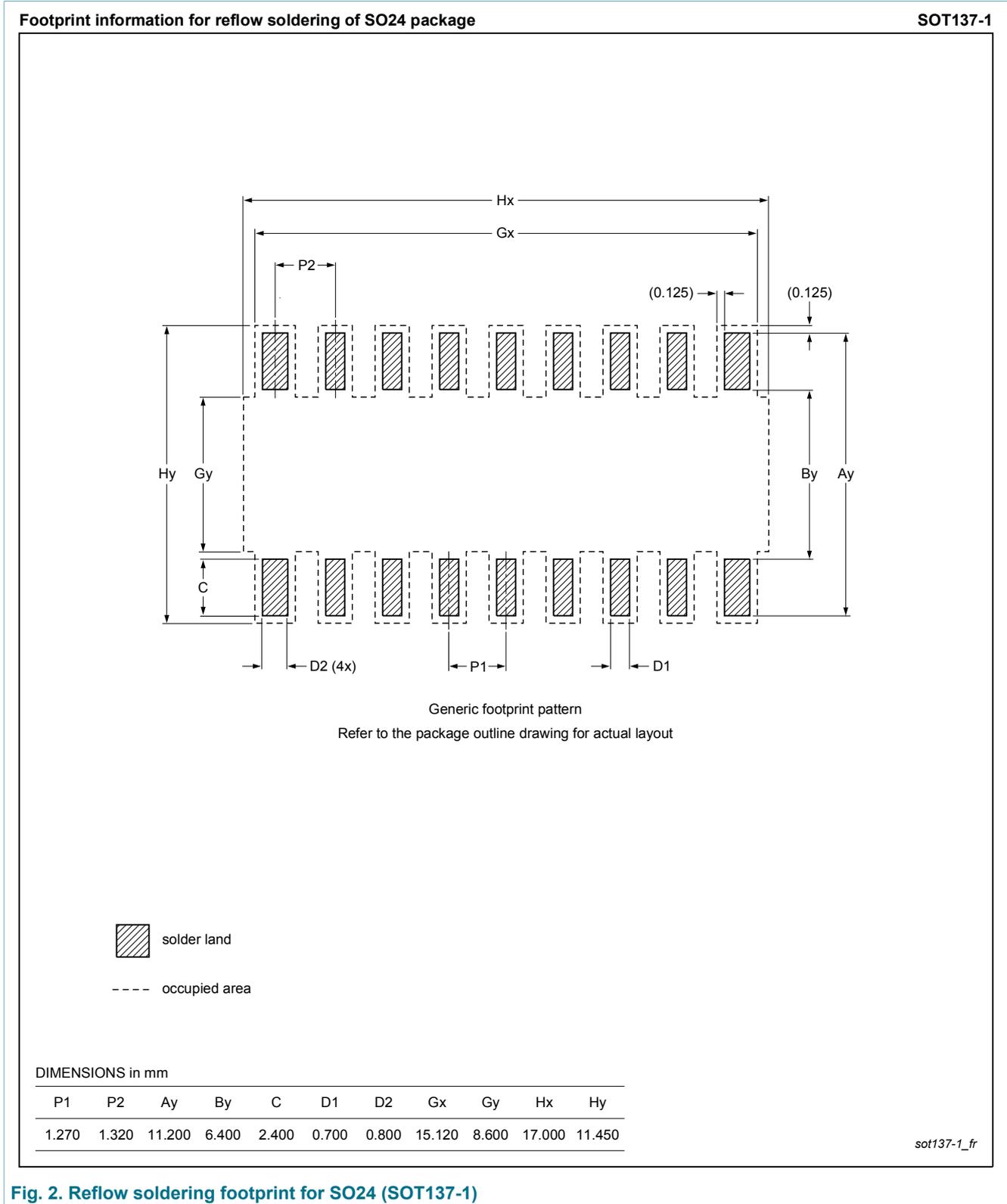


Fig. 2. Reflow soldering footprint for SO24 (SOT137-1)

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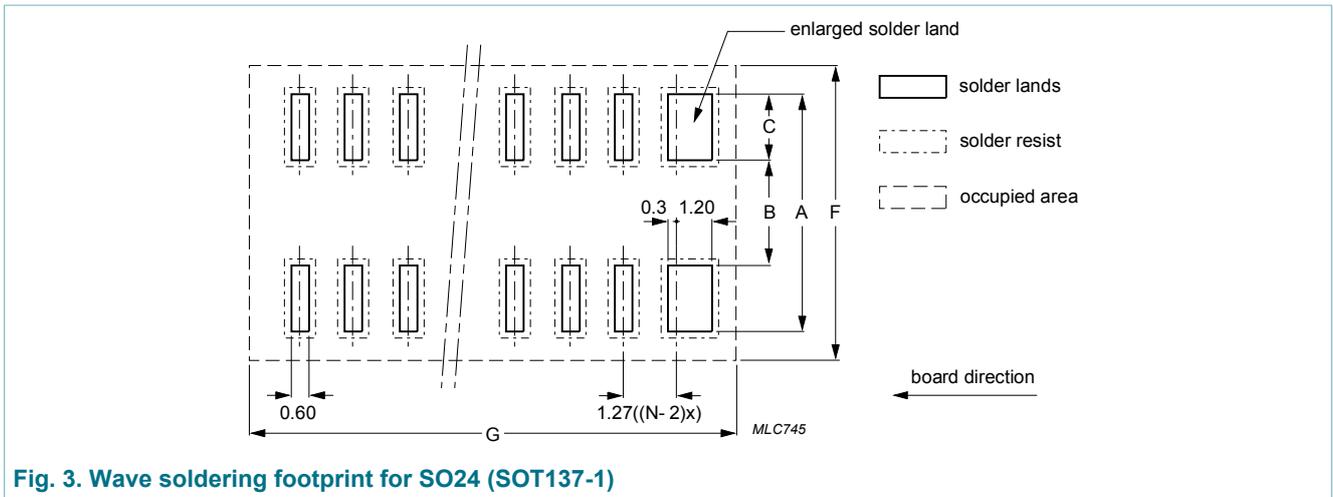


Fig. 3. Wave soldering footprint for SO24 (SOT137-1)

4. Legal information

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